

Electronic Patent Application Fee Transmittal

Application Number:	10811999			
Filing Date:	30-Mar-2004			
Title of Invention:	METHOD OF MANUFACTURING A SEMICONDUCTOR PACKAGE USING A LEAD FRAME HAVING THROUGH HOLES OR HOLLOWS THEREIN			
First Named Inventor/Applicant Name:	Kenichi Shirasaka			
Filer:	Michael J. Scheer/Inga Hildreth			
Attorney Docket Number:	X2007.0158			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180